

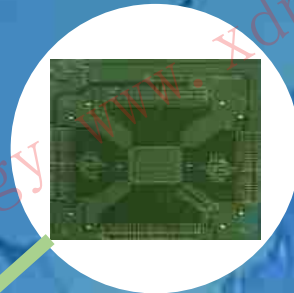


# Xing Da Electric Technology Co., Ltd.

1.PCB Layout



2.Make PCB(1-38layers)



3.Purchase Components



**One-stop Service**

4.Assemble components



5.Housing mold



6.PCBA Test



7.Final Test



— Professional PCB,PCB Assembly and Electronic Components Manufacturer



# CONTENTS

-  1 Company Overview
-  2 Business Model
-  3 Certification
-  4 Production Capacity
-  5 Customer Representatives

# Company Profile



## Xing Da Electric Technology Co., Ltd.

A **professional PCB and PCBA manufacturer**, located in Shenzhen. After many years of development, we have become a group company that integrates research and development, manufacture, SMT, sale, and so on. Our company has set up a subsidiary company in Hong Kong and our subsidiary company is specialized in developing overseas markets.

**We provide one-stop service for our clients, from PCB layout to assembling all components.**

1. PCB layout
2. Make PCB(1-38 layers)
3. Provide all components
4. Assemble all components
5. Writing programming
6. PCBA/finished product Testing



Our factory has advanced production and test equipment from Germany, Taiwan, Japan, and Italy. For example, cut machine from Taiwan, SCHMOLL from Germany, POSALUX from Switzerland, pressure machine from Italy, exposure machine from Japan, V-cut machine from Germany. And import AOI of Camtek and Obotech, and CMI900 advance test equipments, and so on.

In order to ensure the production of high-quality products, we have cultivated a group of innovative, professional, and experienced staff in technology, production, and management. Our team now consists of 700 dedicated employees.

We test and control the quality of products according to American IPC and MIL. We have got UL, CQC TS16949 and ISO14000 certificates, so we can sell safe printed circuit boards and PCBA to all countries over the world.

Our company has been recognized widely with good quality, quick delivery, best service and reasonable prices in many fields, such as automotive electronics, digital communications and electrical instruments, and LED industry sector. Our products are sold well in Asia, Europe and America etc.



## Culture

Honesty, fairness, Profession, innovation!

## Policy

Quality firstly, customer firstly,  
Mutual benefit, develop together

## Vision

Intelligent manufacturing service provider

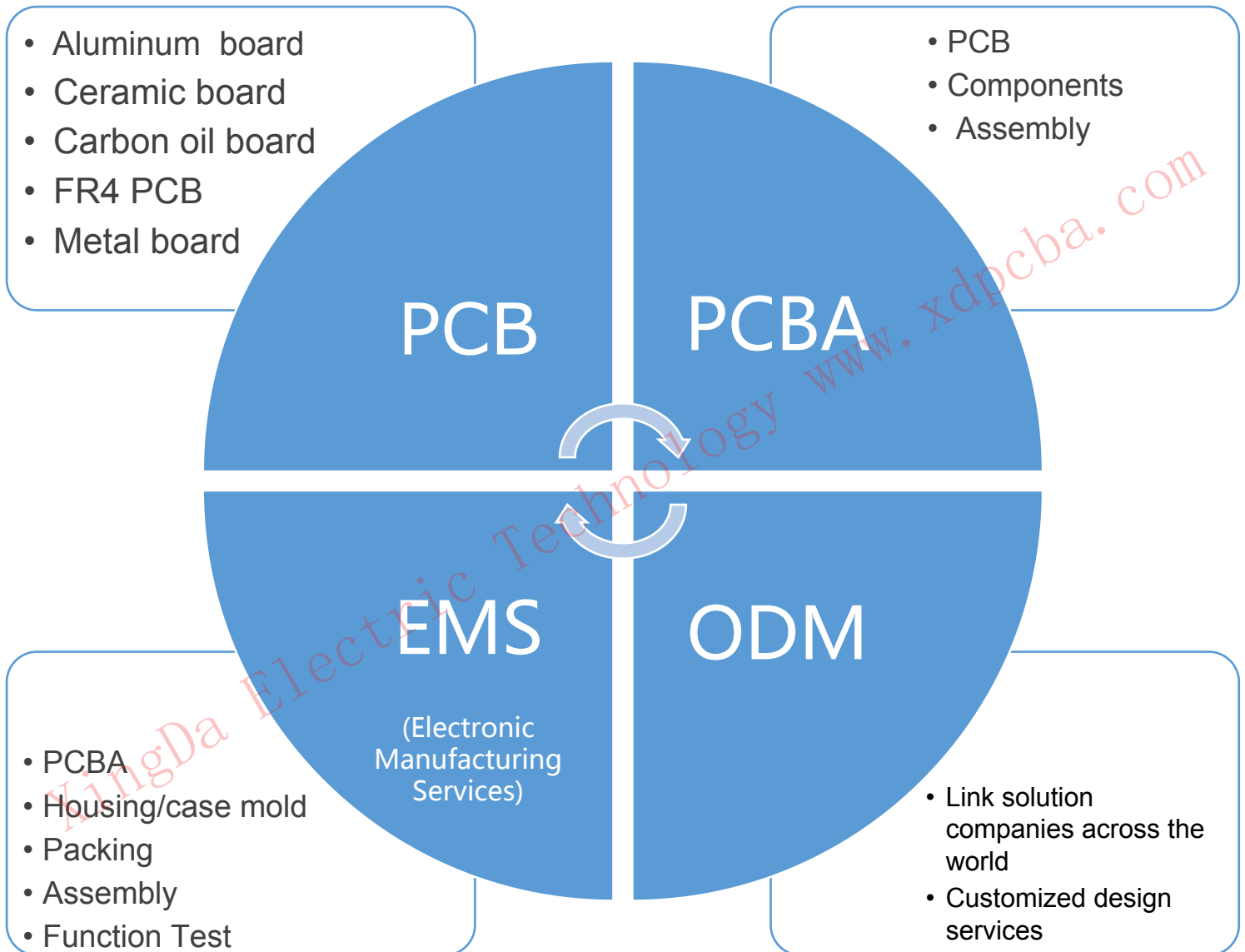
## Mission

One-stop service, smart manufacturing,  
makes your production easier.



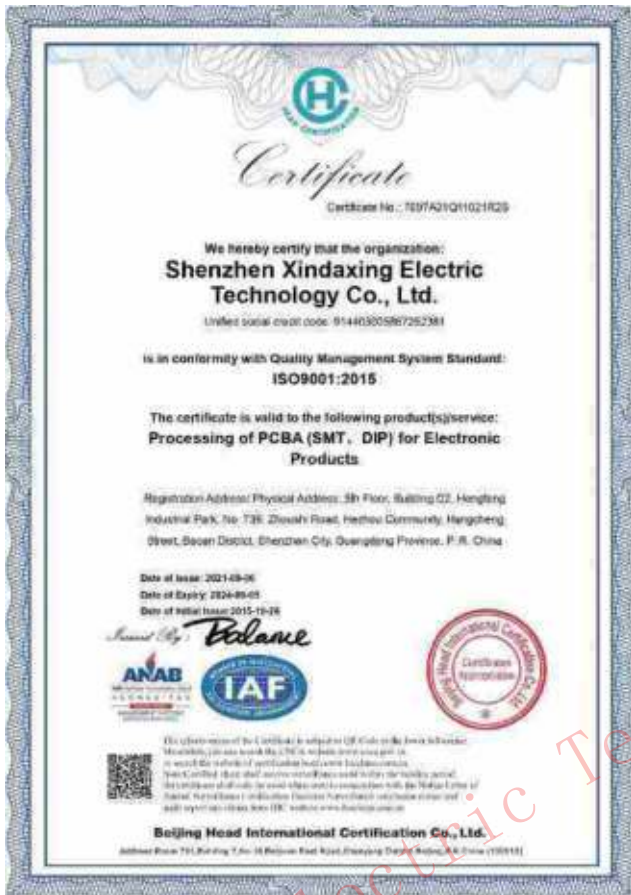


# Business Model





# Certification



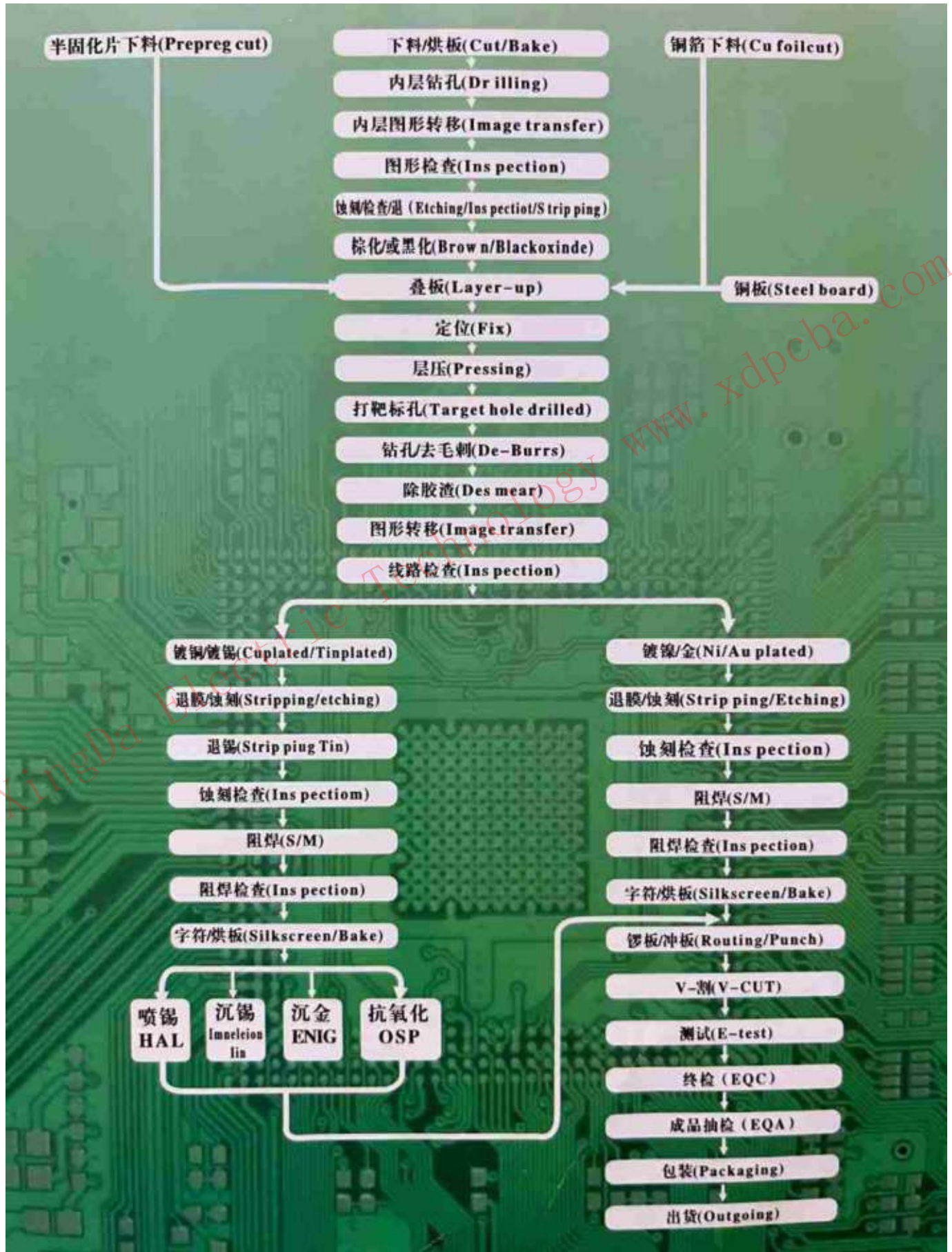


## PCB Manufacture Capacity

Item	Specification
Material	FR-4, FR1,FR2; CEM-1, CEM-3,Rogers, Teflon,Arlon,Aluminum Base, Copper Base,Ceramic, Crockery, etc.
Remarks	High Tg CCL is Available( $T_g \geq 180^\circ\text{C}$ )
Finish Board Thickness	0.2 mm-6.00mm(8mil-126mil)
Surface Finish	Gold finger( $\geq 0.13\mu\text{m}$ ), Immersion Gold(0.025-0075um), Plating Gold(0.025-3.0um), HASL(5-20um), OSP(0.2-0.5um)
Shape	Routing、Punch、V-cut、Chamfer
Surface Treatment	Solder Mask(black, green, white, red, blue, thickness $\geq 12\mu\text{m}$ , Block, BGA)
	Silkscreen(black, yellow, white)
	Peel able-mask(red, blue, thickness $\geq 300\mu\text{m}$ )
Minimum Core	0.075mm(3mil)
Copper Thickness	1/2 oz min; 12oz max
Min Trace Width & Line Spacing	0.075mm/0.075mm(3mil/3mil)
Min Hole Diameter for CNC Drilling	0.1mm(4mil)
Min Hole Diameter for Punching	0.6mm(35mil)
Biggest panel size	610mm * 508mm
Hole Position	$\pm 0.075\text{mm}$ (3mil) CNC Drilling
Conductor Width(W)	$\pm 0.05\text{mm}$ (2mil) or $\pm 20\%$ of original
Hole Diameter(H)	PTH: $\pm 0.075\text{mm}$ (3mil)
	Non PTH: $\pm 0.05\text{mm}$ (2mil)
Outline Tolerance	$\pm 0.1\text{mm}$ (4mil) CNC Routing
Warp & Twist	0.70%
Insulation Resistance	10Kohm-20Mohm
Conductivity	$< 50\text{ohm}$
Test Voltage	10-300V
Panel Size	110 x 100mm(min)
	660 x 600mm(max)
Layer-layer misregistration	4 layers:0.15mm(6mil)max
	6 layers:0.25mm(10mil)max
Min spacing between hole edge to circuitry pattern of an inner layer	0.25mm(10mil)
Min spacing between board outline to circuitry pattern of an inner layer	0.25mm(10mil)
Board thickness tolerance	4 layers: $\pm 0.13\text{mm}$ (5mil)



# Multi-Ager PCB Manufactural Process





# FPC Tech Specification

Items	Capabilities
Layers	FPC : 1 to 6 Layers, Rigid Flex : 2 to 10 Layers
Regular Base Materials	Kapton, Polyimide ( PI ) ,Polyester ( PET )
Base Copper Thickness	1/3 oz to 2oz
Regular Base Material Thickness	12.5um to 50um ( FPC )
	0.1mm to 3.2mm ( Rigid )
Regular Coverlay Thickness	27um to 50um
Regular Adhesive Thickness	12um to 25um
Blind or Buried Vias	Yes
Impedance Control	Yes
Min.Line Width/Spacing	0.04mm/0.04mm
Surface Finishing	Electroplate Ni/Au ( Flash gold/Soft gold/Hard gold ) ,ENIG, Immersion Tin; plated silver;immersion silver ; OSP,HASL
Outline Fabrication	Die cut, laser cut, CNC routing, V-scoring
Hole to edge(Hard tool/Die Cut)	$\pm 0.1/\pm 0.2$ mm
Edge to edge(Hard tool/Die Cut)	$\pm 0.05/\pm 0.2$ mm
Circuit to edge(Hard tool/Die Cut)	$\pm 0.07/\pm 0.2$ mm



# Aluminium Tech Specification

Item	
Type of Alum board	single board, Insulation board, double sided board
Finish Board Thickness	0.4mm----- 3.0mm
Copper Thickness	1 OZ--6 OZ
Min.Trace Width & Line Spacing	0.15mm
Biggest size	120cm*60cm
Type for surface treatment	OSP.HASL, Immersion Gold ,Immersion Tin (lead free)
OSP	0.20-0.40um
Thickness of Ni	2.50-3.50um
Thickness of Au	0.05-0.10um
Thickness of tin	5-20um
Thickness of immersion silver	0.15-0.40um
Thermal conductivity	1.0W-----3.0W
Dielectric Thickness	50um-150um
Thermal resistance	0.05°C/W-1.7°C/W
Minimum completed hole dimension	±0.10mm
Tolerance for Hole Diameter	±0.075mm
Minimum Drilling Hole Diameter	φ0.8mm
Mask between pins	0.15mm-0.35mm
Minimum spacing between Pad and Pad	0.18mm-0.35mm
Outline tolerance	±0.10mm
Minimum thickness for V-cut	0.25mm
Outside copper thickness	18-105um
Core copper thickness	18-35um



## Carbon Oil Tech Specification

<b>Handle PCB( PS2,XBOX.etc)</b>	
Main technical parameter	
Rang of total resistance	1K $\Omega$ -1M $\Omega$
Resistance tolerance:	$\pm 20\%$
Resistance to heat :	260 $^{\circ}$ C $\pm 5^{\circ}$ C , 5sec , $\Delta TR \leq \pm 50\%$
Durability:	1 Million cycles Min

<b>Automobile component(Use for windscreen wiper. light and air-condition)</b>	
Main technical parameter	K-1M $\Omega$
Resistance taper:	linear
Resistance tolerance:	$\pm 1\%$
Linearity tolerance:	$\pm 1\%$
Durability:	1 Million cycles Min
TCR:	with $\pm 1000$ PPM(-30 $^{\circ}$ C-- $+70^{\circ}$ C)

<b>Electricital Component in speed control,etc.</b>	
Main technical parameter	R $\Omega$ -3M $\Omega$
Resistance tolerance:	$\pm 1\%$
Linearity tolerance:	$\pm 1\%$
Durability:	1 Million cycles Min



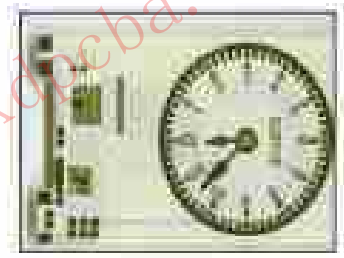
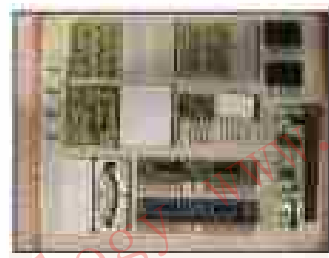
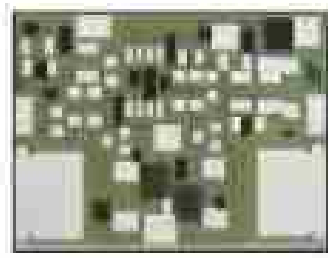
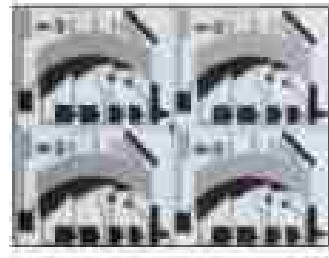
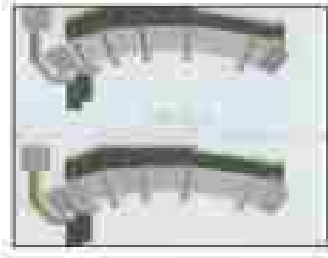
# Ceremic PCB Tech Specification

Item	Test Condition	unite	senior
Material	Aluminium nitride Ceramic /Alumina 99.5%/Alumina 99%		
Color status			
average crystal size		μm	3-5
volume density		g/cm <sup>3</sup>	≥3.74
water absorption		%	0
Vickershardness	Load 4.9	Gpa	≥ 15
flexural Strength	Bending moment 80mm	Mpa	≥324
Linear Coefficient of Thermal Expansion	20-500°C20-800°C	1×10 <sup>-6</sup> mm/°C	605-7.56.5-8.0
thermal conductivity	20°C	W(m-k)	≥ 170
Dielectric intensity		Kv/mm	≥ 12
Volume Resistance	20°C300°C500°C	Ω-cm	≥10 <sup>14</sup> ≥10 <sup>11</sup> ≥10 <sup>9</sup>
Dielectric Constant	1MHz		9.3-10.6
dielectric loss	1MHz		3×10 <sup>-4</sup>
Thermal-shock	850°C	times	≥7
roughness of the surface	Ra(λ2)	μm	0.20-0.75

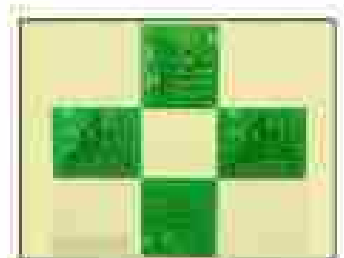
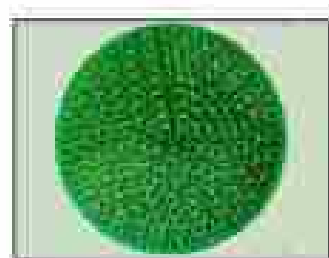
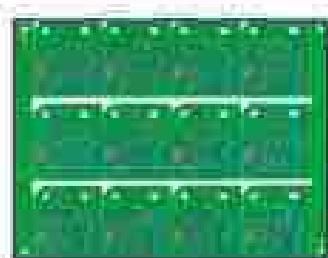
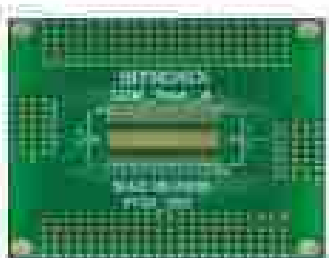
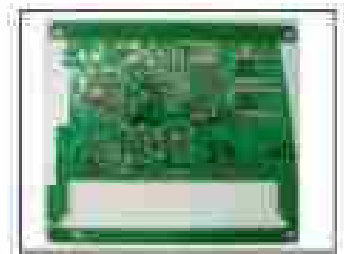
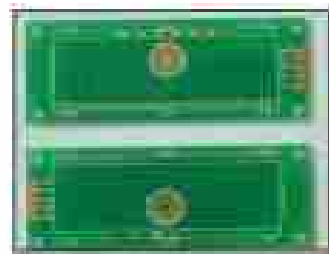
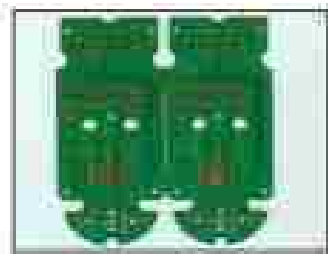
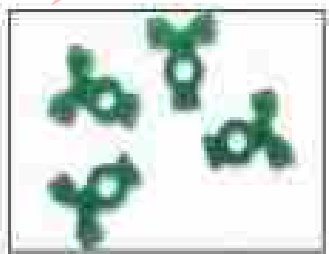
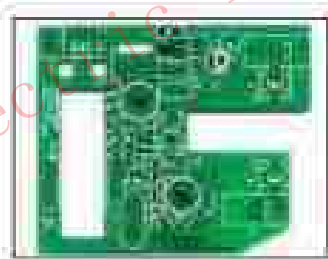


## Feature products

### Ceramic /Pottery/Crockery PCB

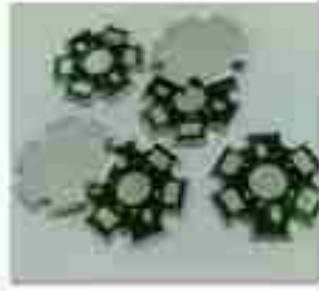


### FR4 PCB





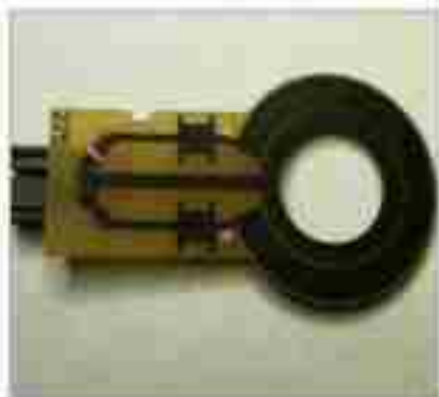
### Metal PCB



### Metal PCB

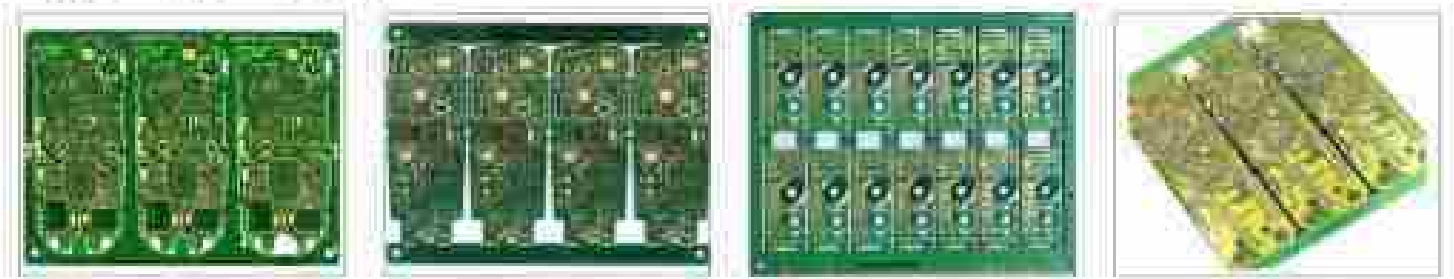


### Carbon Oil PCB

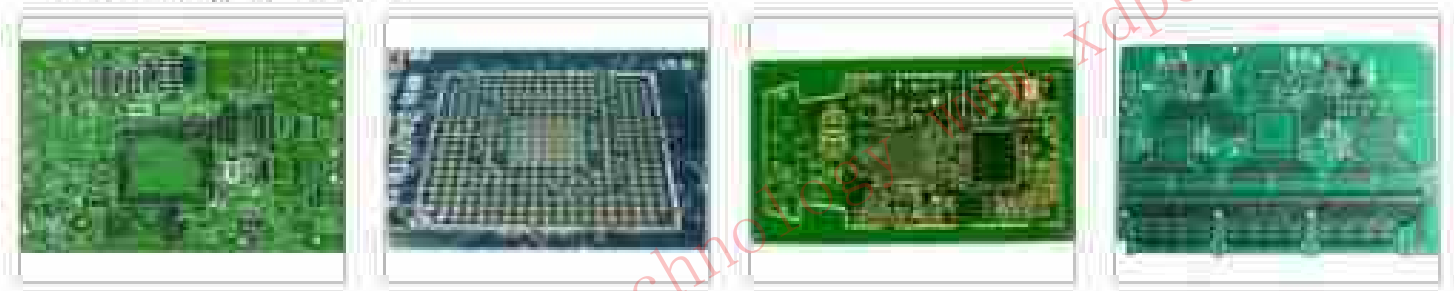




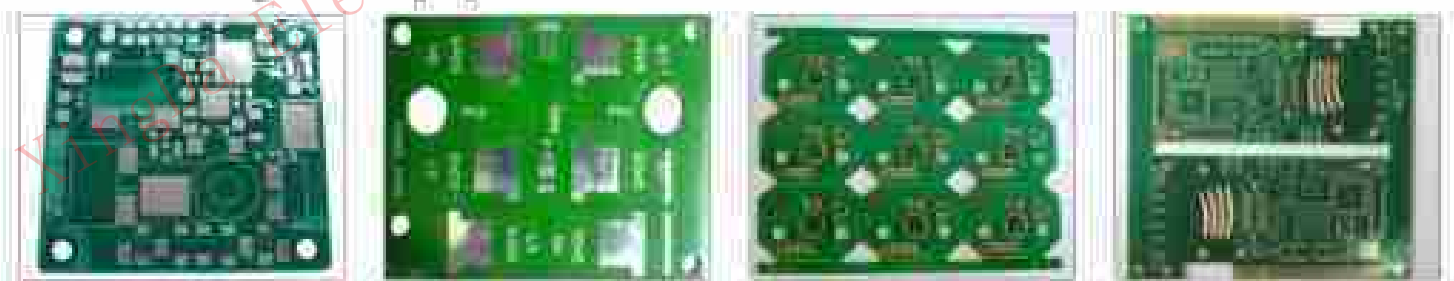
## HDI PCB



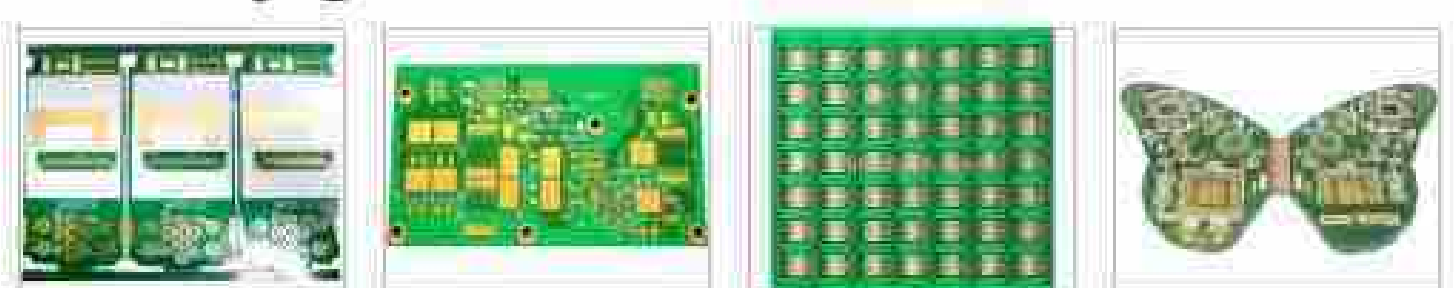
## BGA PCB



## Heavy copper PCB



## Heavy gold/Au PCB





## FPC-Flexible print circuit

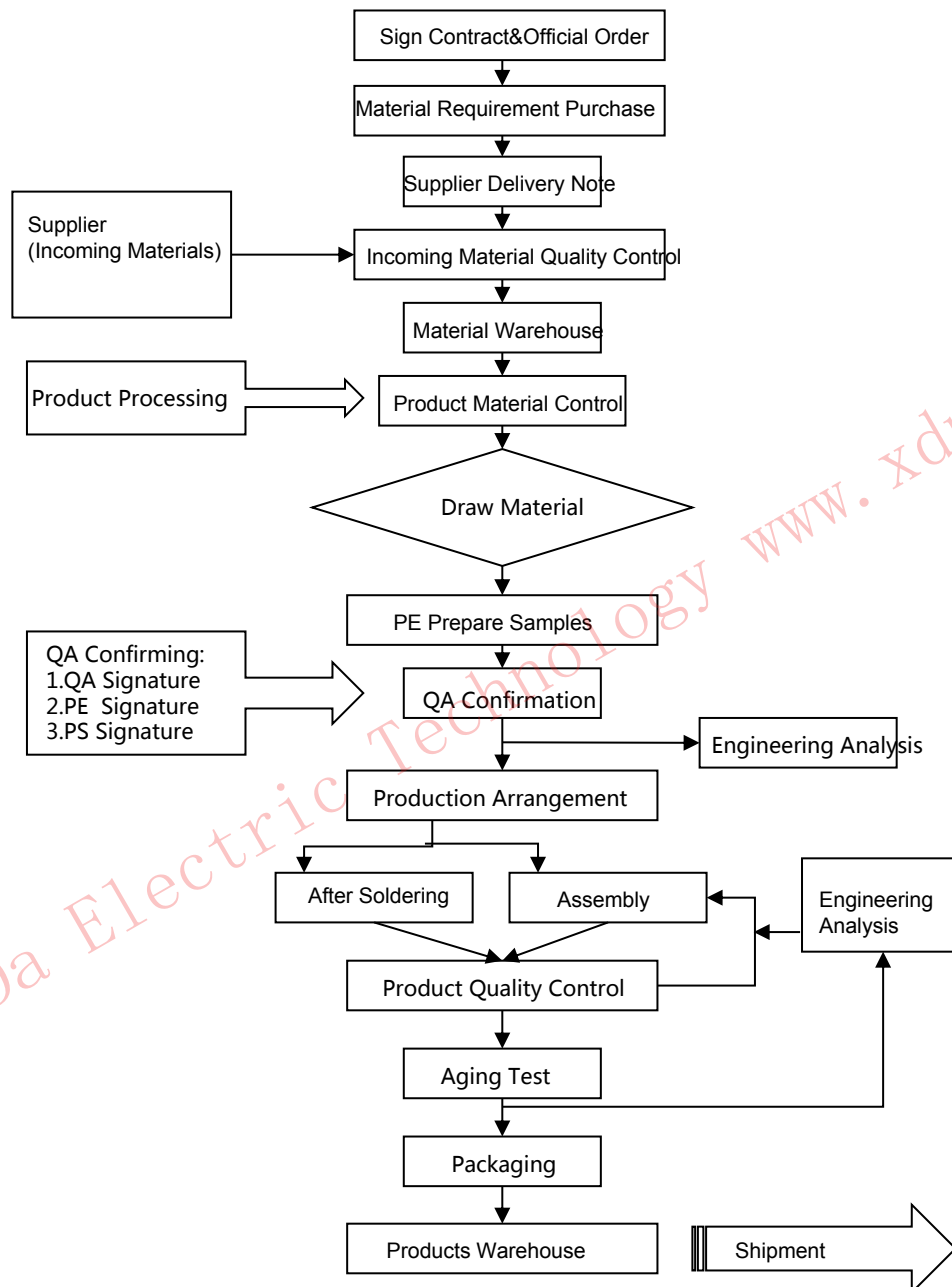


## Rigid-flex PCB





# PCBA Process Chart

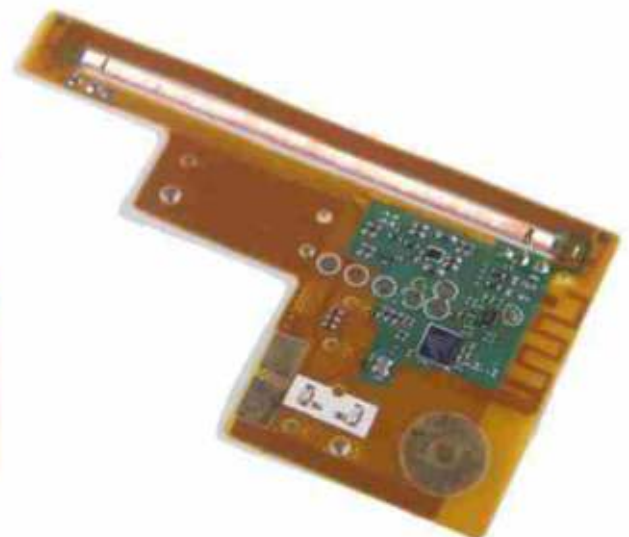
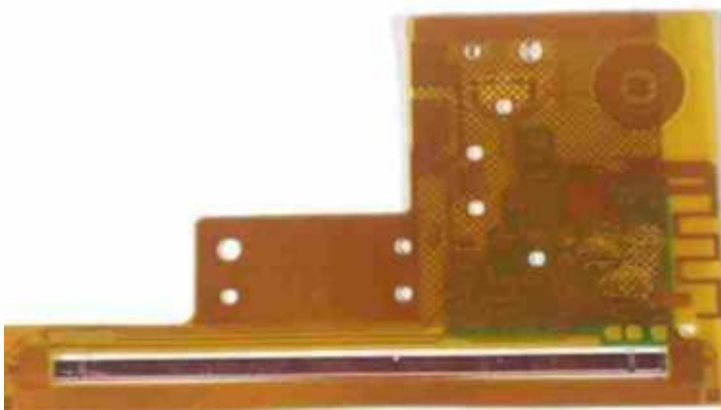
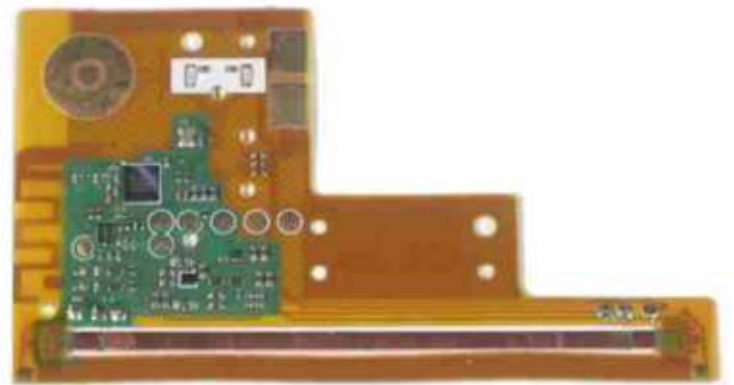
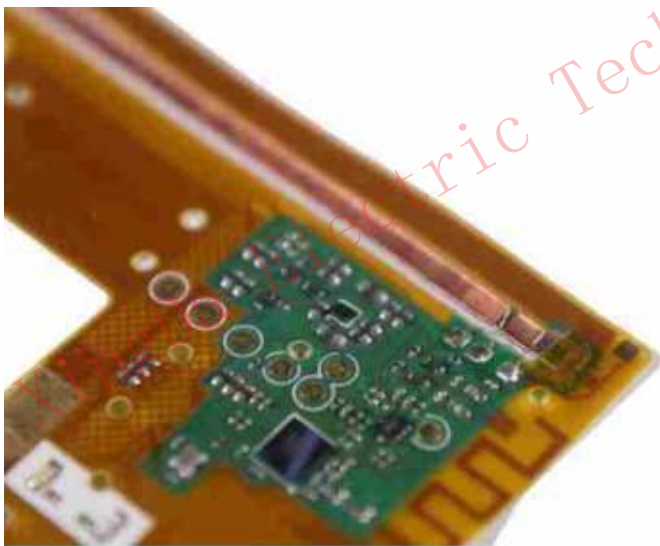
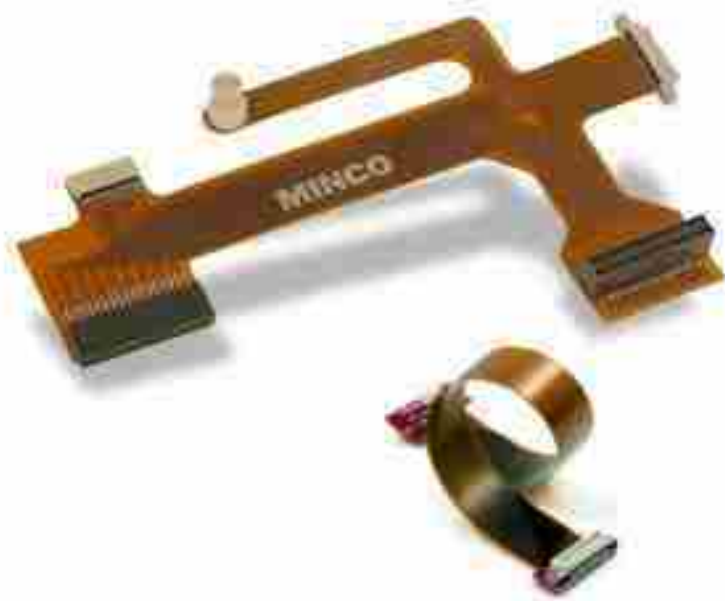


## PCBA Technical requirement:

- 1) Professional Surface-mounting and Through-hole soldering Technology
- 2) Various sizes like 1206,0805,0603 ,0201 components SMT technology
- 3) ICT(In Circuit Test),FCT(Functional Circuit Test) technology.
- 4) PCB Assembly With UL,CE,FCC,Rohs Approval
- 5) Nitrogen gas reflow soldering technology for SMT.
- 6) High Standard SMT&Solder Assembly Line
- 7) High density interconnected board placement technology capacity.



# FPCA



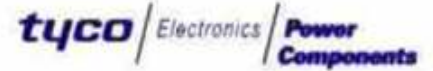


## PCB Assembly





# Customer Representatives



## Russia:



## Italy:



## United States:



## Germany:



## Turkey:



## Slovenia :



## Argentina:



## Portugal:



## Iran:



## Hungary:



## United Kingdom:



## Sweden: Fosieborg AB

## Switzerland: swissponic



## **XingDa Electric Technology Co.,Ltd.**

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